

06/19/00
JC863 U.S. PTO

06-20-00

PTO/SB/05 (4/98)
Approved for use through 09/30/2000 OMB 0651-0032
Patent and Trademark Office U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.
06/19/00
JC863 U.S. PTO
09/596549

Please type a plus sign (+) inside this box → ☒

UTILITY PATENT APPLICATION TRANSMITTAL (Only for new nonprovisional applications under 37 C.F.R. § 1.53(b))	Attorney Docket No.	H-525US
	First Inventor or Application Identifier	Andrew Booth, et al.
	Title	Thick Film Heater Apparatus
	Express Mail Label No.	EK353419605 US

APPLICATION ELEMENTS <i>See MPEP chapter 600 concerning utility patent application contents.</i>	ADDRESS TO: Assistant Commissioner for Patents Box Patent Application Washington, DC 20231	
1. <input checked="" type="checkbox"/> * Fee Transmittal Form (e.g., PTO/SB/17) (Submit an original and a duplicate for fee processing)	5. <input type="checkbox"/> Microfiche Computer Program (Appendix)	
2. <input checked="" type="checkbox"/> Specification [Total Pages 26] (preferred arrangement set forth below) <ul style="list-style-type: none">- Descriptive title of the Invention- Cross References to Related Applications- Statement Regarding Fed sponsored R & D- Reference to Microfiche Appendix- Background of the Invention- Brief Summary of the Invention- Brief Description of the Drawings (if filed)- Detailed Description- Claim(s)- Abstract of the Disclosure	6. Nucleotide and/or Amino Acid Sequence Submission (if applicable, all necessary) <ul style="list-style-type: none">a. <input type="checkbox"/> Computer Readable Copyb. <input type="checkbox"/> Paper Copy (identical to computer copy)c. <input type="checkbox"/> Statement verifying identity of above copies	
3. <input checked="" type="checkbox"/> Drawing(s) (35 U.S.C. 113) [Total Sheets 7]	ACCOMPANYING APPLICATION PARTS 7. <input checked="" type="checkbox"/> Assignment Papers (cover sheet & document(s)) 8. <input type="checkbox"/> 37 C.F.R. § 3.73(b) Statement <input type="checkbox"/> Power of Attorney (when there is an assignee) 9. <input type="checkbox"/> English Translation Document (if applicable) 10. <input type="checkbox"/> Information Disclosure Statement (IDS)/PTO-1449 <input type="checkbox"/> Copies of IDS Citations 11. <input type="checkbox"/> Preliminary Amendment 12. <input checked="" type="checkbox"/> Return Receipt Postcard (MPEP 503) (Should be specifically itemized) 13. <input type="checkbox"/> * Small Entity Statement(s) <input type="checkbox"/> Statement filed in prior application, Status still proper and desired (PTO/SB/09-12) 14. <input type="checkbox"/> Certified Copy of Priority Document(s) (if foreign priority is claimed) 15. <input type="checkbox"/> Other:	
4. Oath or Declaration [Total Pages <input]<ul="" type="checkbox"/> a. <input checked="" type="checkbox"/> Newly executed (original or copy) b. <input type="checkbox"/> Copy from a prior application (37 C.F.R. § 1.63(d)) (for continuation/divisional with Box 16 completed)<ul style="list-style-type: none">i. <input type="checkbox"/> <u>DELETION OF INVENTOR(S)</u> Signed statement attached deleting inventor(s) named in the prior application, see 37 C.F.R. §§ 1.63(d)(2) and 1.33(b).		
* NOTE FOR ITEMS 1 & 13: IN ORDER TO BE ENTITLED TO PAY SMALL ENTITY FEES, A SMALL ENTITY STATEMENT IS REQUIRED (37 C.F.R. § 1.27), EXCEPT IF ONE FILED IN A PRIOR APPLICATION IS RELIED UPON (37 C.F.R. § 1.28).		
16. If a CONTINUING APPLICATION, check appropriate box, and supply the requisite information below and in a preliminary amendment: <input type="checkbox"/> Continuation <input type="checkbox"/> Divisional <input type="checkbox"/> Continuation-in-part (CIP) of prior application No. _____ Prior application information. Examiner _____ Group / Art Unit _____ For CONTINUATION or DIVISIONAL APPS only: The entire disclosure of the prior application, from which an oath or declaration is supplied under Box 4b, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference. The incorporation can only be relied upon when a portion has been inadvertently omitted from the submitted application parts.		

17. CORRESPONDENCE ADDRESS				
<input checked="" type="checkbox"/> Customer Number or Bar Code Label 24132 or <input type="checkbox"/> Correspondence address below (Insert Customer No. or Attach bar code label here)				
Name	Eric Spencer			
Address				
City	State	Zip Code	05468	
Country	Telephone	802-859-8429	Fax	Fax: 802-859-8325

Name (Print/Type)	Eric Spencer, Esq.	Registration No. (Attorney/Agent)	39,383
Signature	<i>Eric Spencer</i>	Date	6/16/00

Burden Hour Statement This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO Assistant Commissioner for Patents, Box Patent Application, Washington, DC 20231.

Attorney Docket: H-525US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Andrew Booth, et al.

Serial No.: Not yet Assigned

Group Art Unit:

Filed:

Examiner:

For: Thick Film Heater Apparatus

Assistant Commissioner for Patents
Washington, D.C. 20231

TRANSMITTAL LETTER

Sir:

Enclosed are the following items for filing in connection with the above-referenced Patent Application:

1. New Utility Transmittal;
2. Fee Transmittal Form (in duplicate)
3. 26 pages of specification, claims and abstract;
4. 7 sheets of Informal Drawings;
5. Declaration and Power of Attorney
6. Recordation Form Cover Sheet and Assignment; and
7. Domestic Representative Election

Please charge all fees relating to this application to Deposit Account #501388. Please stamp and return the enclosed self-addressed return postcard as a receipt.

Dated: 6/16/00

Respectfully submitted,

By Eric Spencer
Eric Spencer
Registration No.: 39,383
Husky Injection Molding, Inc.
288 North Road
Milton, VT 05468
(802) 859-8429

Domestic Representative

Date: *JUNE 16, 2000*

Attorney Docket No.: H-525US
Invention Title: Thick Film Heater Apparatus
First Inventor's Name: Andrew Booth, et al.

Assignment Receiving Name: Husky Injection Molding, Ltd.
Address: 500 Queen Street South
Bolton, Ontario, Canada L7E 5S5

The following domestic representative is hereby appointed by the receiving party to receive communications from the United States Patent & Trademark Office in relation to the above captioned patent application.

Eric Spencer
Reg. No. 39,383
288 North Road
Milton, Vermont 05468
Phone: 802-859-8429
Fax: 802-859-8325

By: *AP Booth*

Date: *6-16-00*

Husky Injection Molding Systems, Ltd.

In the United States Patent and Trademark Office

June 16, 2000

File Number: H-525US

Invention of

Andrew Booth, Jim Pilavdzic, Peter Wolff, Edward Jenko
Bernd Winkelmann and Harold Warren

For a

Thick Film Heater Apparatus

I hereby certify that this correspondence is being deposited with the United States Postal Service using "Express Mail to Addressee" in an envelope with sufficient postage addressed to: Commissioner of Patents and Trademarks, Washington D.C. 20231 on 6/19/00.

(Date)

Express Mail No.: EK3534960545

Print Name: ERIC SPENCER

Sign: Eric Spencer

Date of Sign.: 6/19/00

In the United States Patent and Trademark Office

Background of the Invention

Field of the Invention

The invention relates to injection molding systems and
5 specifically to a heater for hot runner nozzles for such
systems.

Related Prior Art

Common to all devices for processing thermoplastic
10 polymeric resins are associated means for obtaining and
maintaining thermoplasticity of the resin during processing,
such as the shaping of the resin material into an article.
Maintenance of thermoplasticity may require both heating and
cooling of the resin at various times in the processing of the
15 resin. Cooling may be needed to avoid thermal degradation of the
resin. Almost all of the resin processing techniques rely at
least in part on heating or cooling of the polymeric resin by
thermal transfer through the agency of a metal surface, part of
the processing apparatus. Heat is generally applied to an
20 outside surface of the metal apparatus by concentrated heat
sources such as band heaters, or from within the body of the
metal part by heater rods or circulating, heated fluids such as
air, water or other chemical liquids. In all cases, the metal
heat transferring components have to be of substantial thickness
25 and mass to resist extreme pressures and mechanical forces. The
large metal mass responds slowly to changes in thermal input or
cooling so that precise control of narrow temperature ranges is
difficult to control. Also, when temperature differences are
desired in adjacent zones of the same apparatus, it is difficult
30 to localize the particular and different temperatures to be
maintained for appreciable periods of time. This shortcoming is
especially troublesome for relatively complex processing

techniques and apparatus, such as in the injection molding of large parts.

Hot runner injection molding systems have several melted material flow passageways that are uniformly heated over the entire flow path leading from a molten reservoir to a mold cavity or cold runner. The melted material that flows through the passageway must remain liquid until reaching the mold cavity or cold runner. To control flow rate and pressure, the heated passageway leads to or from injection mold runner nozzles which may be externally heated. This nozzle is sometimes referred to as a hot runner gate injection nozzle or a hot runner probe injection nozzle but will hereafter be simply referred to as a "runner nozzle." These runner nozzles are typically located in the hot runner molding system's manifold base. The nozzles extend through ports leading to each of the molding cavities or to a secondary heated or unheated passageway within a mold block. It is essential to adequately and uniformly heat the runner nozzle because this is often the final point in the heated portion of the flow passageway just prior to being injected into the mold. At this point the material must be at or above its melting point in order for the molten material to flow freely through the runner nozzle, so the nozzle can reliably perform its function of controlling flow rate.

Significant transitions in temperature at the point of the runner nozzle are not desirable as the nozzle is a key part of any molding process because transitions in temperature may change the fluid consistency of the melted material such as thermoplastic which may result in a defective final product. Also, if it is desired to intermittently shut off flow and turn flow back on for a given nozzle, heating of the nozzle is

necessary to maintain the residual material in a melted state, to prevent clogging.

Currently, runner nozzles are typically heated by a
5 heat source external to the nozzle. Typically, the runner nozzle
is heated by a resistive wire proportionally spirally wound
heating element. The spirally wound element forms a cylinder
that is co-axially disposed about the exterior surface of the
runner nozzle. However this type of heater configuration
10 operates inefficiently due to heat loss because of the open
exposure of the heating element to the surrounding environment.
It also increases the diameter of the nozzle and thus requires
bigger openings in the manifold plate to receive the nozzle.
Also, many of the standard nozzle heaters are not completely
15 encapsulated by an insulated sheath, which make it more
difficult to maintain a temperature at the runner nozzle
location that is uniform with the remainder of the flow
passageway. In addition the physical design of the resistive
element (i.e. spiral) is limited as well. The gauge of the
20 resistive wire heating element required to generate enough heat
is such that the wire cannot be formed into complex circuit
patterns. In many cases various complex circuit patterns other
than a simple spiral pattern are desired in order to achieve
more efficient heat distribution. Also, these types of heaters
25 can be bulky and difficult to maintain and repair. Installation
is difficult because of the large leads of the resistive
element, and the mold designer must allocate space for the large
leads and increased nozzle/heater combination. In addition, in
many cases the externally heated runner nozzle apparatus has to
30 be adapted to accommodate a thermocouple device which requires
an additional space for the thermocouple and its wiring. A
better way is needed to uniformly heat the runner nozzle, heat

it efficiently and the design should be cost effective and easy to maintain and repair.

Conventional industrial equipment which provides heat
5 externally to a flow passage, such as the subject runner nozzle, will generally provide heat by the means described above or by a single or multiple band heater design.

In U.S. Pat. No. 5,973,296 to Juliano, et al., the
10 invention is a tubular heater that consists of a metallic tubular substrate that has a dielectric film layer and a resistive thick film layer applied directly to the exterior cylindrical surface of a tubular substrate by the method of precision fine film printing. This method is similar to the
15 method used to produce some thick-film resistors. The precision fine film printing requires the use of an expensive fine film printing machine that uses a fine tip writing pen to dispense the conductive ink.

U.S. Pat. No. 5,411,392 to Von Buren, teaches a
20 slotted band heater in conjunction with a slotted clamping sleeve that installs over a hot runner nozzle. This two part device utilizes the clamping force of the outer sleeve to maintain thermal communication between the band heater and the
25 nozzle.

In U.S. Pat. No. 4,922,082 to Bredt et al., an
electrical resistive heating device which comprises two co-axially spaced apart electrodes, each in intimate surface-to-surface contact with an interposed heating element is disclosed.
30 The heating element comprises a powdered material which functions as an electrical resistive heater when an electrical potential difference is applied thereacross by the electrodes.

Heat generated in such element is conducted through at least one of the electrodes which in turn conducts it to an object which it is desired to heat. The powdered material is pressed in the annular space between the two electrodes.

5

A new heating device is needed that can be easily installed over a runner nozzle or other conduit and be readily massed produced, reliable, provide repeatable and predictable temperature profiles at a reduced manufacturing and maintenance cost.

10

The improved apparatus of the present invention includes as a heater means a multi-layer thick-film heater which may be mounted in close association with the thermoplastic polymeric resins being processed in the apparatus. Heavy metal components to achieve thermal transfer to the resin are not necessary. There can be a saving of weight, materials and labor in manufacture. With the closer juxtaposition of the heating element in the subject plastic, a closer control of resin temperature is maintainable with quicker response times to maintain a pre-determined resin temperature, even in adjacent but different zones or localities. The lower thermal mass of the heating elements is more responsive to cooling or changes from heating to cooling or cooling to heating. A more accurate and repeatable temperature profile can be obtained with the device resulting in improved machine performance and a higher quality finished product.

15

20

25

Summary of the Invention

The primary objective of the invention is to provide an improved heater apparatus for use in the processing of molten material.

Another object of the invention is to provide a substantially thin tube like heater device that can be easily installed on a typical hot runner nozzle with a reduce overall diameter of the nozzle which allows for a reduction in the spacing between nozzles.

A further object of the invention is to provide a heater that is lower in cost to manufacture and maintain.

Yet another object of the invention is to provide a heater that is suitable for mass production quantities through the use of the silk-screening process.

Another object of the invention is to provide a thick-film heater with a unique slip-on and slip-off electrical connector feature that can survive the high temperatures and thermal expansion difficulties inherent in an injection molding machine.

Yet another object of the invention is to provide a more reliable heater that also exhibits a more stable and repeatable temperature profile over its usable life.

Still another object of the present invention is to provide a heater that can provide an optimized and precise temperature profile along its length.

Yet another object of the present invention is to provide a heater with a multi-layer resistive trace that increases the heater output for a given size heater substrate.

5 The foregoing objects are achieved by the installation of the present invention in an injection molding machine, particularly on the hot runner nozzle system. The present invention includes a cylindrically shaped metal substrate with a silk screened dielectric layer applied thereon. Silk screened
10 or otherwise printed on the dielectric layer is a resistive layer which comprises a predetermined trace pattern with two ends, the pattern of the trace determines the temperature profile along the length of the heater. The resistive trace could comprise multiple layers of resistive material connected
15 serially to increase the heater capacity. Silk screened in communication with the two terminal ends of the resistive trace pattern are electrical contact pads which are designed to interface with a pair of electrical conductors for communication of an electrical current therethrough. Silk screened over the
20 resistive trace pattern is an insulation layer that protects the resistive layer from abrasion and electrical shorting. The insulation layer could further be formulated to act as a thermal insulator to decrease thermal losses from the outer surface of the heater. The insulation layer is not placed over the
25 electrical contacts. The electrical conductors are placed and rigidly affixed to the electrical contact pads by the use of a removable connector sleeve that slips over the outside diameter of the heater and over the contact pads. There is no welding, brazing or soldering of the conductors to the contact pads.
30 Contact at this interface is maintained by the wedging action and pressure created by the connector sleeve.

BREIF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a cross sectional view of the preferred embodiment installed on a typical hot runner nozzle assembly;

5

FIG. 2a is a plan view of a preferred embodiment with the connector sleeve removed for clarity;

FIG. 2b is a simplified cross sectional view of a preferred embodiment;

10

FIG 2c is an isometric view of a preferred embodiment with the connector sleeve removed for clarity;

FIG. 3 is a cross sectional detailed view of the various layers of a preferred embodiment;

15

FIG. 4 is a simplified isometric view of the connector sleeve installed on the heater;

20

FIG. 5 is a cross sectional view of the connector sleeve installed in the heater;

FIG. 6 is a graph of the temperature profile along the length of a hot runner nozzle showing the prior art as well as a preferred embodiment of the invention;

25

FIG. 7 is a plan view of the electrical connector assembly;

30

FIG. 8 is a cross sectional view of the locking detent assembly;

FIG. 9 is a flat layout of the thick film resistive/conductive trace pattern.

5

REFERENCE NUMERALS USED IN THE DRAWINGS

- 8 - hot runner nozzle assembly
- 10 - preferred embodiment
- 10 12 - heater assembly
- 14 - nozzle body
- 16 - channel
- 18 - connector sleeve assembly
- 20 - nozzle tip
- 15 22 - conductor
- 24 - slot
- 26 - dielectric layer
- 28 - resistive layer
- 30 - locating hole
- 20 32 - insulation layer
- 34 - contact pads
- 35 - detent groove
- 36 - connector housing
- 37 - first contact groove
- 25 38 - locking detent assembly
- 39 - second contact groove
- 40 - contact
- 42 - key
- 44 - detent pin
- 30 46 - detent spring
- 48 - low resistance conductive trace
- 50 - resistive trace

- 5

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

Referring to FIG. 1, a typical hot runner nozzle assembly 8 is shown. The hot runner nozzle assembly 8 comprises a nozzle body 14, a channel 16, a nozzle tip 20, a heater assembly 12, a connector sleeve assembly 18 and at least a pair of conductors 22. The channel 16 runs the length of the nozzle body 14 and communicates with the nozzle tip 20 for transfer of molten material to a mold cavity (not shown). Placed in thermal communication with the nozzle body 14 is the heater assembly 12 which maintains the material in channel 16 in a free flowing molten state. The connector sleeve assembly 18 is slidably installed over the heater assembly 12 and rigidly affixes the conductors 22 with the heater assembly 12 for communication of electrical current therethrough.

Referring now to FIG. 2a, 2b, 2c, and FIG. 3, the heater assembly 12 is shown. The heater assembly 12 comprises an optional slot 24, a locating hole 30, a substrate 34, a thick-film dielectric layer 26, a thick-film resistive layer 28, at least a pair of contact pads 35 and an insulation layer 32. The heater assembly 12 comprises various layers of different materials. The substrate 34 in the preferred embodiment is a C-shaped piece of metal, typically made from steel or other thermally conductive material. The optional slot 24 runs the length of the heater and allows the substrate to act as a self clamping spring when installed around the nozzle body 14. In the preferred embodiment the substrate 34 is made from 430 stainless steel machined from solid bar or tube to have approximately 0.020" to 0.040" thick cylindrical wall.

The inner diameter of the substrate 34 is sized smaller than the outside diameter of the hot runner nozzle. This configuration provides good thermal communication between the heater assembly 12 and the nozzle body 14. As mentioned previously, in the preferred embodiment the substrate 34 is made from type 340 or 430 stainless steel which has substantially the same or optionally slightly lower thermal coefficient of expansion as the thick-film layers that are applied thereon. Alternatively, the substrate could be made from a ceramic composite material formulated to provide a particular thermal coefficient of expansion. Matching the thermal coefficient of expansion is essential to prevent cracking in the layers as the elements start to expand during heating. If the substrate were to expand more than the thick-film layers, the thick-film layers would start to crack and may cause the resistive layer 28 to short out prematurely. In addition, the coefficient of thermal expansion for the substrate 34 is lower than that of the nozzle body 14. As a result, as the nozzle body 14 heats up, it expands quicker than the substrate 34 and a natural clamping force is built up between the heater assembly 12 and nozzle body 14, resulting in improved thermal communication.

Referring to FIG. 3, the thick-film dielectric layer 26 is applied to the outer surface of the substrate 34, with the preferred embodiment using a silk-screen type process. The silk-screen process is preferable because it greatly reduces the production time of a specific heater design. The silk-screen process requires the use of a single mask for the dielectric layer, and the silk-screen process is well suited for high speed processing. In the preferred embodiment, the dielectric layer is made from a ceramic-glass mixture and provides electrical insulation between the substrate 34 and the resistive layer 28.

The dielectric layer 26 is applied to the outside of the substrate 34 and then cured in an oven at 850°C. In the preferred embodiment the dielectric layer 26 has a minimum dielectric strength between 1000-1500 VAC and an insulation resistance greater than 100 mega-ohms. To achieve this dielectric strength usually requires the application of at least three successive thick-film layers of the dielectric material.

The term "thick-film" is used in the art to describe materials that are on the order of 0.001" thick after firing. As opposed to "thin-film" which is used in the art to describe much thinner materials on the order of 0.00025" thick. Thick-film materials are typically applied as a paste or ink and fired using a precise thermal profile. Thick-film materials may be applied using either silk-screen or direct write technologies. Thick-film ink comprises a finely ground suspension of ceramics or glass matrix with varying combinations of conductor and resistive materials. Thick-film ink can easily be formulated to be used as a conductor, resistor or insulator.

Applied over the dielectric layer in a predetermined trace pattern is the thick-film resistive layer 28. The resistive layer 28 is essentially the electrical circuit that generates heat through ohmic losses within the trace. Referring to FIG. 9, which shows a preferred embodiment of a flat pattern of the resistive layer 28, the resistive layer 28 is made from both a resistive trace 50 and a low resistance conductive trace 48. Heat is generated mostly from the resistive trace 50, thereby applying heat at very precise and controlled locations along the heater assembly 12. The conductive trace 48 is made of very low electrically-resistive material to minimize ohmic losses.

In the preferred embodiment, both the resistive trace 50 and the conductive trace 48 is applied to the dielectric layer 26 using a silk-screen process. Alternatively, the resistive trace could be applied using a direct write method utilizing a special printer. A direct write method is preferable in small lot production environments where economies of scale are not realized. Again, the silk-screen process is preferable due to lower manufacturing cost for large volume applications. The conductive trace 48 is made from a palladium silver matrix that typically exhibits a resistance on the order of 0.01 ohms/square. The conductive trace 48 is applied before the resistive trace 50 because the conductive trace is fired at approximately 825⁰ C, and the resistive trace 50 is fired at approximately 800⁰ C. Following the firing of the conductive trace 48, the resistive trace 50 is applied using the silk-screen process. As mentioned previously this trace is then fired at approximately 800⁰ C.

The patterning of the resistive layer 28 is a key advantage of the present invention. Thermal profiling is a key design element in hot runner nozzle construction. The repeatability and high watt density available with the present invention allows for an optimized thermal profile which will help to eliminate troublesome hot spots in hot runner nozzles. The trace pattern used on the preferred embodiment can easily be modified based on computer thermal analysis to provide the heat exactly where it is needed. In the preferred embodiment, watt densities on the order of 100 Watts per cubic centimeter have been achieved.

During the formation of the conductive trace 48, at least two contact pads 50 are formed from the same material. The contact pads 50 in the preferred embodiment are located at each end of the resistive layer 28 and provide a place to apply electrical power to the heater assembly 12. The contact pads 50 are located in a predetermined position on the heater assembly 12 for interface with the connector sleeve assembly 18 when the sleeve is fully installed and locked in place.

Applied over the resistive layer 28 is the insulation layer 32 also using a silk-screen process. The insulation layer 28 is not applied over the contact pads 35. The insulation layer 32 is a mechanical, thermal and electrical insulative substance that protects the resistive layer 28 from abrasion and electrical shorts and reduces heat loss from the outside surface of the heater. The insulation layer 32 comprises a glass matrix which is fired at a temperature of approximately 600⁰ C.

Referring to FIG. 4 and FIG. 5, the connector sleeve 18 is shown installed on the heater assembly 12. The connector sleeve assembly 18 comprises a connector housing 36, electrical spring contacts 40, electrical conductors 22, passageways 54, a detent groove 35, a first and second contact groove 37 and 39 respectively, and a locking detent assembly 38.

The connector housing 36 is an annular shaped plug that will slidably engage the outside diameter of the heater assembly 12. A key 42 on the inside diameter of the housing 36 interfaces with the slot 24 and properly aligns the sleeve assembly 18 with the contact pads 35. The first and second contact grooves 37 and 39 are formed on the inside surface of the connector housing 36 for the insertion of spring contacts

40. The passageways 54 allow for the installation of the conductors 22 through the wall of the housing 36 for connection to the contacts 40.

5 The connector housing 36 in the preferred embodiment is made from a pressed and fired 96% dense alumina ceramic material. This material currently offers properties that are best suited for high temperature environments and exhibits electrical and thermal insulative properties. It could however
10 be easily manufactured from any suitable material that possesses high dielectric properties and good thermal conductivity.

15 The electrical spring contacts 40 are used to transmit electrical energy from the conductors 22 to the contact pads 35 on the surface of the heater assembly 12. The spring contacts 40 must be compliant to compensate for the thermal expansion, corrosion resistant and able to withstand a temperature of 425° C continuously without degradation while maintaining a low resistance connection. In the preferred embodiment, the
20 material for the spring contact 40 is made from full hard stainless steel, preferably type 301. The contact surface of the spring contact 40 may be gold plated to improve corrosion resistance and reduce contact resistance.

25 Referring to FIG. 7, the spring contact 40 is welded to the conductor 22. In the preferred embodiment, the conductor 22 is resistance welded to the contact 40 because it reduces the heat transmitted to the wire and requires no fluxing or filler material. This type of connection is also able to withstand the
30 high temperature molding process. In the preferred embodiment a high temperature wire is used with a teflon or fiberglass insulator applied.

Referring to FIG. 4, FIG. 5 and FIG. 8, the locking detent assembly 38 is shown. The detent assembly 38 is inserted in the detent groove 35. The detent groove 35 runs the length of the housing 36, and is wide enough to fully seat the detent assembly 38. The detent assembly 38 comprises a detent spring 46 and a detent pin 44. When the housing 36 is installed on the heater assembly 12, the detent pin 44 is aligned and communicates with the locating hole 30. This alignment automatically occurs when the key 42 engages the slot 24 of the heater assembly 12. The detent spring 46 is made from a sheet material that exhibits spring like characteristics that can withstand the high temperatures of the molding process. In the preferred embodiment the detent spring 46 is made from type 301 stainless steel. As the connector sleeve assembly 18 is slid down the heater assembly 12, the detent pin 44 is sized to engage the locating hole 30 and effectively locks the connector sleeve assembly 18 onto the heater assembly 12 in the proper location and insures the alignment and communication of electrical current through the spring contacts 40 and the contact pads 35.

As mentioned previously, the ability to provide an optimized resistive trace 50 based on a computer analysis is a major advantage of this invention. Referring to FIG. 6, a graph is shown that compares the various temperature profiles along the length of the nozzle body based on various heater technologies. A wound cable heater profile 56 shows how hot spots can be generated in the nozzle. This type of heater quickly creates a hot spot in the center portion of the nozzle body and can degrade the quality of the molten material. Also shown is a copper sleeve heater temperature profile 58. Again,

this type of heater, while better than a wound cable heater, still exhibits hot and cold spots that can degrade the quality of the molten material. An optimized computer model trace 60 is shown that shows the best temperature profile for processing
5 molten material in a hot runner nozzle. With the present invention, the resistive trace 50 was designed to approach this optimized performance. Curve 62 shows the actual measured performance of the optimized heater design of the present invention. This temperature profile comes close to the
10 optimized computer model and will result in improved performance of the molding process.

The present invention may effectively be employed on any channel means from a source of molten plastic. One skilled
15 in the art could easily utilize the present invention on different processing machines that require the application of heat in specific areas of the machine for continued processing of material therein. The present invention could easily be employed on hot runner channels within a manifold or on a sprue
20 bar or on an injection machine plastisizing screw housing for example.

Thus the assembly of the present invention is easy to install, has a low profile enabling more compact design
25 possibilities, provides a controllable and optimized heat profile and represents a lower cost heater solution with efficient heat exchange capabilities.

It is to be understood that the invention is not
30 limited to the illustrations described and shown herein, which are deemed to be merely illustrative of the best modes of carrying out the invention, and which are susceptible of

20

What is claimed is:

1. In an injection molding machine, a heater comprising,
 - a) a thermally conductive substrate surface;
 - b) a silk-screened dielectric layer applied on said substrate surface;
 - c) a resistive layer applied on said dielectric layer thereby forming a circuit for the generation of heat;
 - d) at least a pair of silk-screened contact pads applied in electrical communication with said resistive layer for electrical connection to a power source;
 - e) an insulation layer applied over said resistive layer; and
 - f) a connector housing for mechanical connection of a contact to each said contact pad, thereby eliminating the need for soldering, brazing or other phase altering connection means.
2. The heater of claim 1, where said substrate is a non-flat surface.
3. The heater of claim 2, where said non-flat surface is cylindrical.
4. The heater of claim 1, where said substrate further comprises a longitudinal slot running the entire length of said substrate.

5. The heater of claim 1, where said resistive layer further comprises a resistive trace and a low-resistance conductive trace, thereby forming an optimized heat generating pattern.
6. The heater of claim 5, where said resistive trace is silk-screened on said dielectric layer.
7. The heater of claim 5, where said conductive trace is silk-screened on said dielectric layer.
8. The heater of claim 1, where said resistive layer is silk-screened on to said dielectric layer.
9. The heater of claim 1, where said resistive layer is direct printed on to said dielectric layer.
10. The heater of claim 1, where said connector housing further comprises a locking detent that engages a locating hole on said substrate.
11. The heater of claim 10, where said locking detent is selectably removable from said locating hole.
12. The heater of claim 10, where said detent and said locating hole are in a predetermined arrangement relative to said contacts, thereby ensuring electrical communication of said contacts to said contact pads when said detent engages said hole.
13. The heater of claim 1, where said connector housing further comprises a key for slidably

engaging a longitudinal slot in said substrate,
thereby aligning radially said contacts with said
contact pads.

5

14. The heater of claim 1, where said connector
housing is made from a ceramic material.

15. The heater of claim 1, where said substrate is a
nozzle body.

10

16. The heater of claim 1, where said substrate is
made from steel.

15

17. The heater of claim 1, where said dielectric layer
has a dielectric strength between 1000 VAC to 1500
VAC and an insulation resistance of at least 100
mega-ohms.

20

18. The heater of claim 1, where said substrate and
said dielectric layer and said resistive layer and
said insulation layer have substantially the same
coefficient of thermal expansion.

25

19. The heater of claim 18, where said substrate has a
slightly lower coefficient of thermal expansion
than said dielectric, resistive and insulation
layer.

30

20. The heater of claim 1, where said resistive layer
is applied to said dielectric layer by
photoforming.

21. The heater of claim 1, where said resistive layer is formed by laser or abrasive etching.

5 22. The heater of claim 1, where said contact is made from gold plated steel.

23. The method of heating comprising the steps of:

10 a) silk-screen printing a thick-film dielectric layer on a thermally conductive substrate;

b) printing a thick-film resistive layer on said substrate forming an electrical trace for generating heat through ohmic losses;

15 c) silk-screen printing at least a pair of contact pads in electrical communication with said resistive layer;

d) silk-screen printing an insulation layer over said resistive layer;

20 e) engaging an electrical contact on each said contact pad using an annular connector housing;

f) electrically powering said electrical contacts.

25 24. The method of claim 23, where said substrate is a cylindrical surface.

25. The method of claim 24, where said substrate further comprises a longitudinal slot running the entire length of said substrate.

30 26. The method of claim 23, where said substrate, dielectric layer, resistive layer and insulation

layer have substantially equal coefficients of thermal expansion.

27. The method of claim 24, where said substrate, dielectric layer, resistive layer and insulation layer have substantially equal coefficients of thermal expansion.

28. An injection mold runner nozzle having a co-axially disposed cylindrical heater comprising:

- a) a cylindrical, thermally conductive substrate with a slot running the entire length of said substrate, said substrate having a smaller coefficient of thermal expansion than said nozzle, thereby causing said substrate to further clamp onto said nozzle as said nozzle and said substrate heat up;
- b) a silk-screened dielectric layer applied on said substrate;
- c) a resistive layer applied on said dielectric layer thereby forming an electrical circuit for heat generation;
- d) at least a pair of silk-screened contact pads applied in electrical communication with said resistive layer for electrical connection to a power source;
- e) an insulation layer applied over said resistive layer; and
- f) an annular connector housing that slidably engages said substrate for mechanical connection of a contact to each said contact pad.

Abstract

Improved injection molding machine heater apparatus
using thick-film layers applied directly on a thermally

5 conductive substrate or directly onto the melt channel.

Preferably, the substrate is cylindrically shaped with a slot
running the length of the substrate. The thick film layers and
substrate have substantially equal coefficient of thermal

expansion. Preferably, the heater assembly has a lower
10 coefficient of thermal expansion than the machine channel it is
installed on so as to increase the thermal communication as they
heat up. A heat resistant connector housing is slidably

installed over the heater assembly for mechanical connection of
conductors to the heater without the use of soldering, brazing,
15 welding or other failure prone connection means.

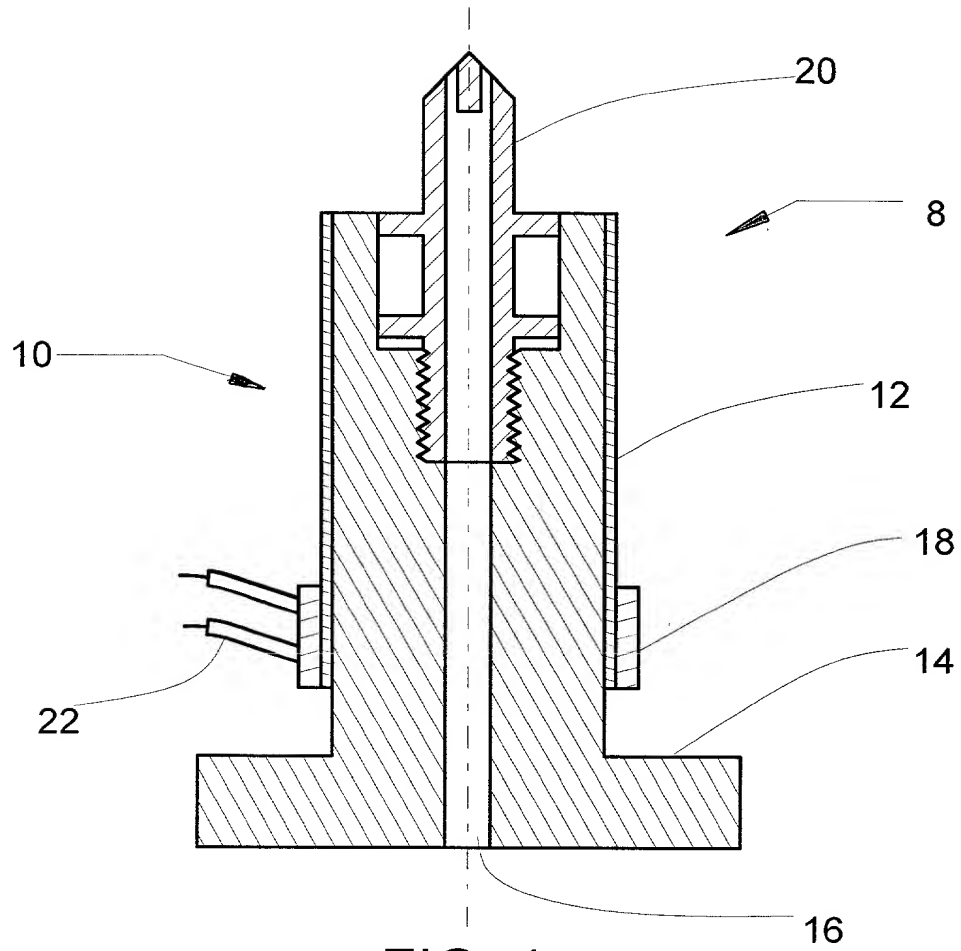


FIG. 1

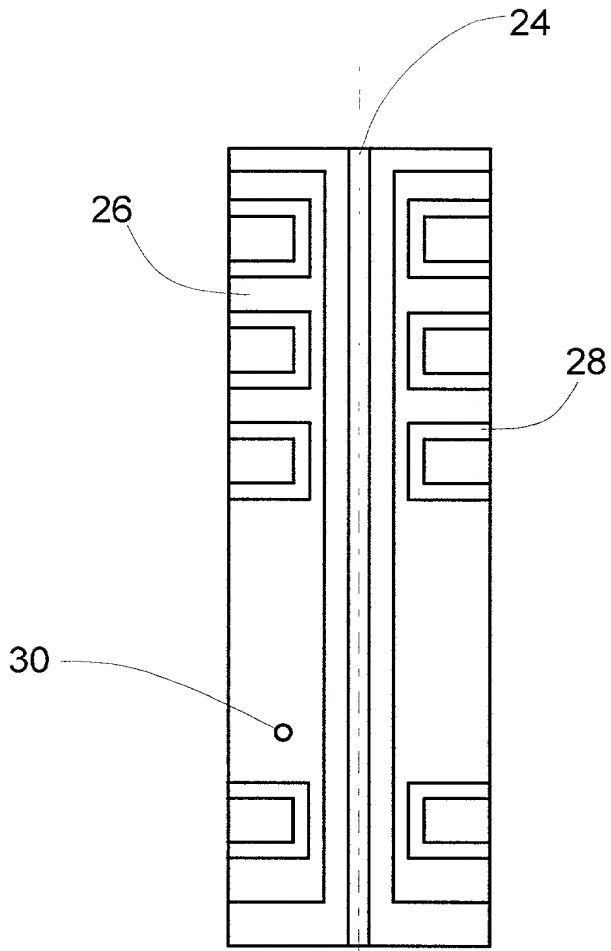


FIG 2a

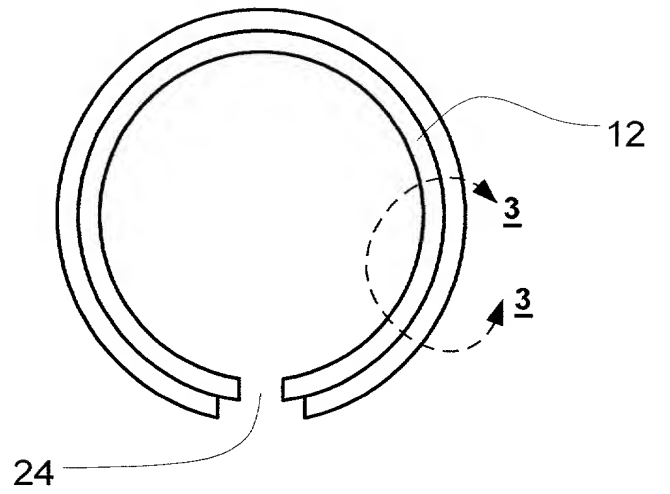


FIG 2b

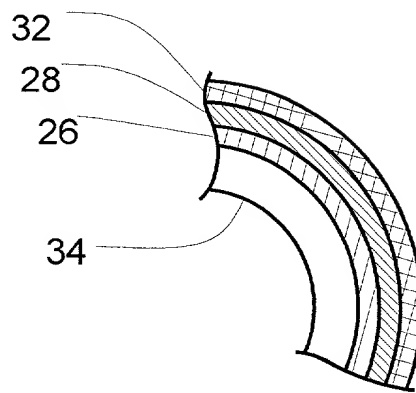
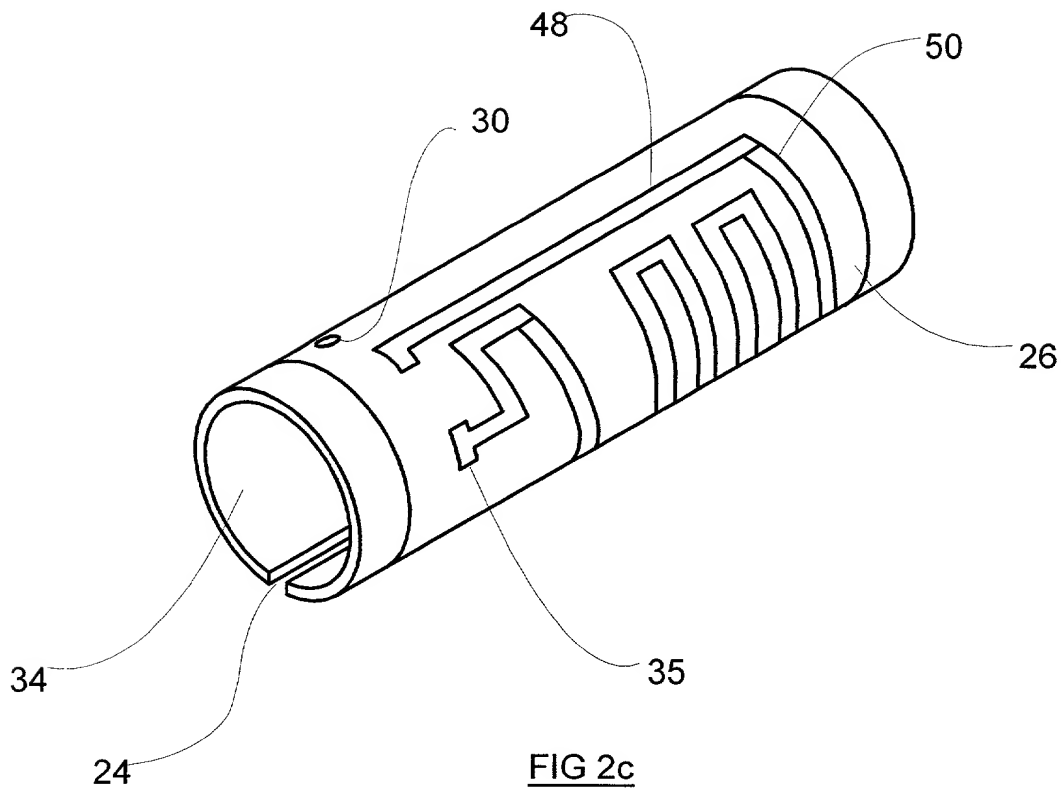


FIG 3



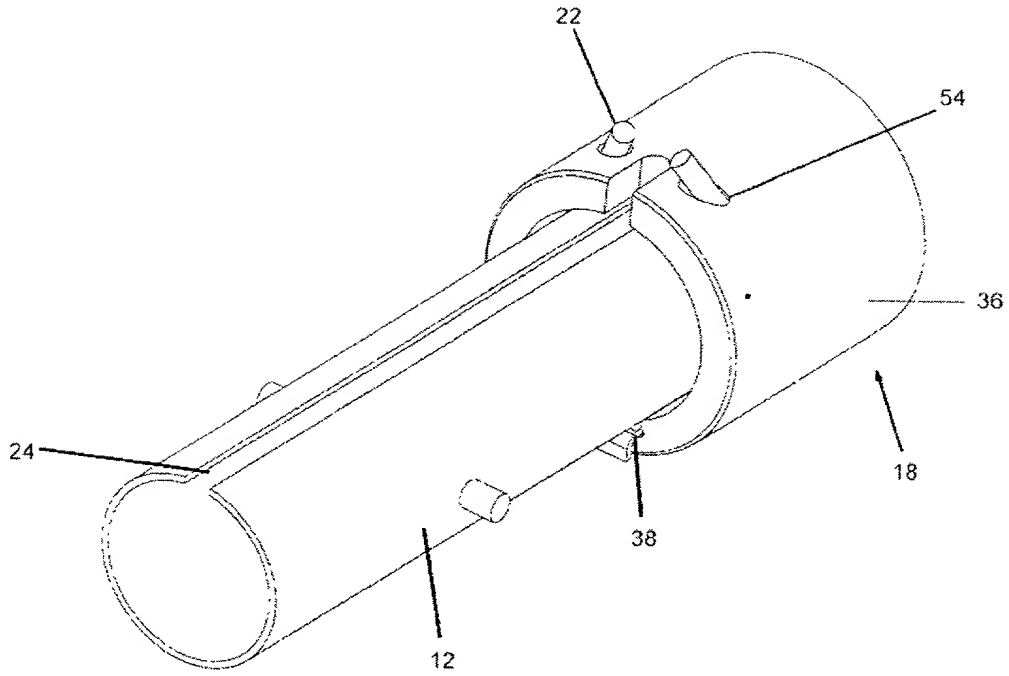


FIG. 4

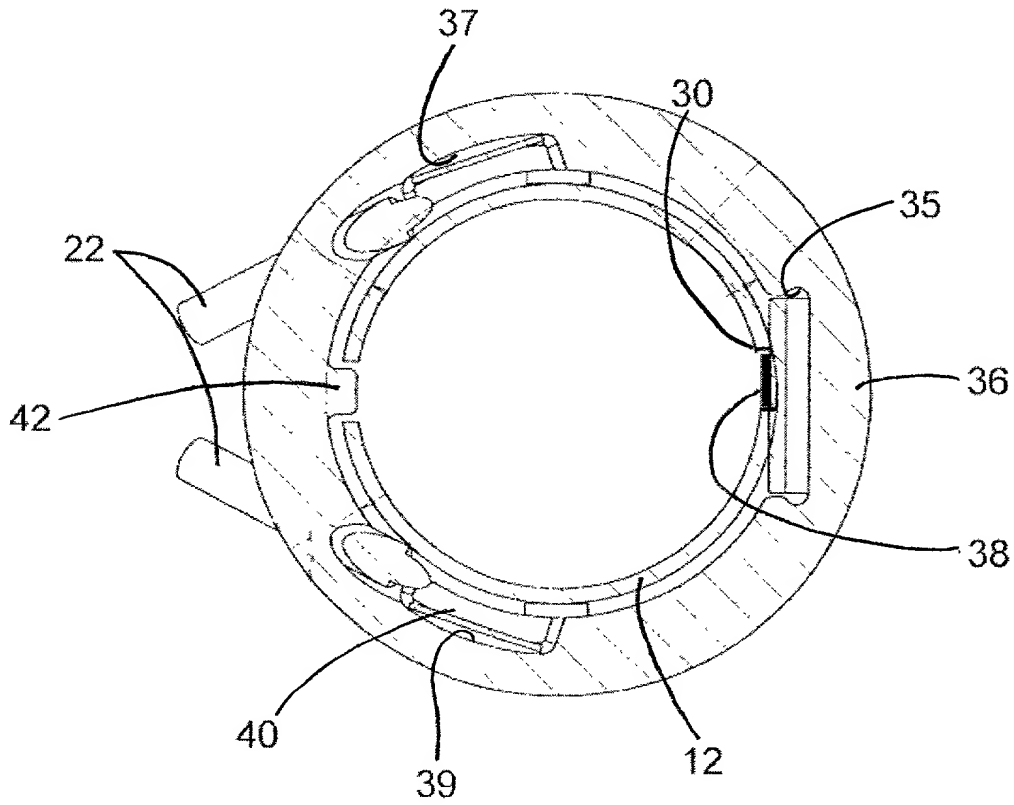


FIG. 5

5/7

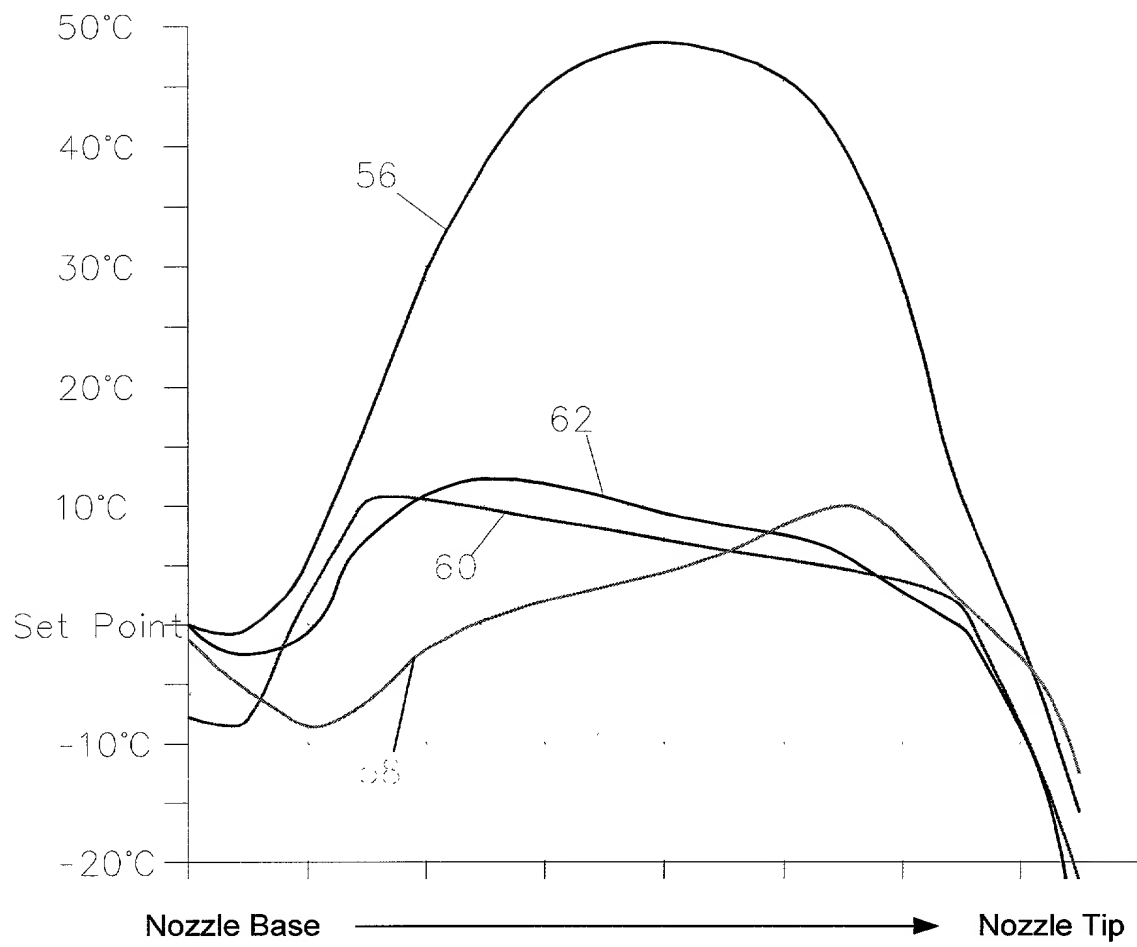


FIG. 6

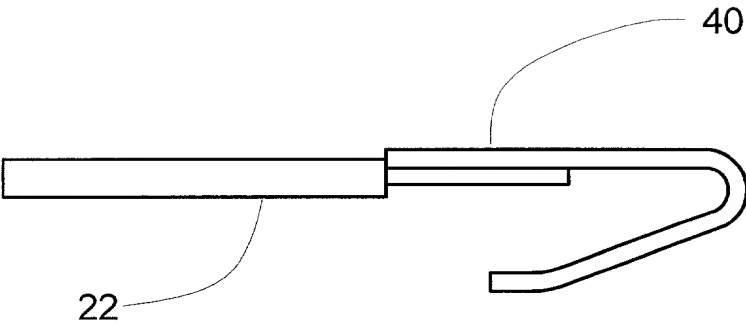


FIG 7

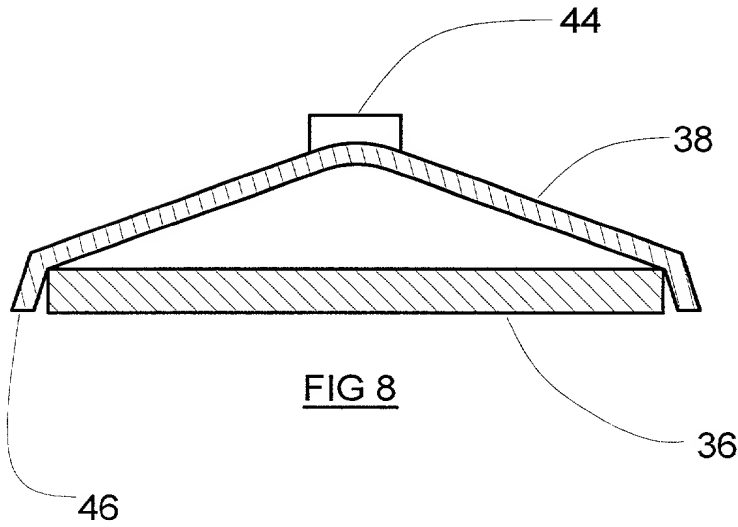


FIG 8

2025-04-24 10:00:00



Please type a plus sign (+) inside this box → **+**

PTO/SB/01 (12-97)

Approved for use through 9/30/00. OMB 0651-0032

Patent and Trademark Office, U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION (37 CFR 1.63) <input checked="" type="checkbox"/> Declaration Submitted with Initial Filing OR <input type="checkbox"/> Declaration Submitted after Initial Filing (surcharge (37 CFR 1.16 (e)) required)	Attorney Docket Number	H-525US
	First Named Inventor	Andrew Booth, et al
	COMPLETE IF KNOWN	
	Application Number	/
	Filing Date	
	Group Art Unit	
	Examiner Name	

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Thick Film Heater Apparatus

the specification of which (Title of the Invention)

☒ is attached hereto
OR
☐ was filed on (MM/DD/YYYY) [] as United States Application Number or PCT International Application Number [] and was amended on (MM/DD/YYYY) [] (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed

Prior Foreign Application Number(s)	Country	Foreign Filing Date (MM/DD/YYYY)	Priority Not Claimed	Certified Copy Attached?	
				YES	NO
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

☐ Additional foreign application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below

Application Number(s)	Filing Date (MM/DD/YYYY)

☐ Additional provisional application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

[Page 1 of 2]

Burden Hour Statement This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231

Please type a plus sign (+) inside this box → ☐

PTO/SB/01 (12-97)
Approved for use through 9/30/00 OMB 0651-0032
Patent and Trademark Office, U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

DECLARATION — Utility or Design Patent Application

I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application

U.S. Parent Application or PCT Parent Number	Parent Filing Date (MM/DD/YYYY)	Parent Patent Number (if applicable)

☐ Additional U.S. or PCT international application numbers are listed on a supplemental priority data sheet PTO/SB/02B attached hereto.

As a named inventor, I hereby appoint the following registered practitioner(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

☒ Customer Number

24132

OR

☐ Registered practitioner(s) name/registration number listed below

Place Customer
Number Bar Code
Label here

Name	Registration Number	Name	Registration Number
Eric Spencer	39, 383		

☐ Additional registered practitioner(s) named on supplemental Registered Practitioner Information sheet PTO/SB/02C attached hereto.

Direct all correspondence to: ☒ Customer Number or Bar Code Label



OR ☐ Correspondence address below

Name	Eric Spencer					24132
Address	Husky Injection Molding Inc.					PATENT TRADEMARK OFFICE
Address	288 North Road					
City		State		ZIP	05468	
Country	USA	Telephone	802-859-8429	Fax	Fax: 802-859-8325	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon

Name of Sole or First Inventor:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle (if any))			Family Name or Surname				
Andrew			Booth				
Inventor's Signature					Date	6/16/00	
Residence: City	Williston	State	VT	Country	USA	Citizenship	USA
Post Office Address	117 Hanon Drive						
Post Office Address							
City	Williston	State	VT	ZIP		Country	

☒ Additional inventors are being named on the _____ supplemental Additional Inventor(s) sheet(s) PTO/SB/02A attached hereto

Please type a plus sign (+) inside this box → ☐

PTO/SB/02A (3-97)
Approved for use through 9/30/98. OMB 0851-0032
Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

DECLARATION

ADDITIONAL INVENTOR(S)
Supplemental Sheet
Page 1 of 2

Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
HAROLD H. MARION				WARREN			
Inventor's Signature	H. Marion Warren					Date	6-16-00
Residence: City	SUGAR GROVE	State	NC	Country	USA	Citizenship	USA
Post Office Address 389 WARDS BRANCH Rd.							
Post Office Address							
City	SUGAR GROVE	State	N.C.	ZIP	28679	Country	USA
Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
WINK BERND				WINKELMANN			
Inventor's Signature	Bernd Winkelmann					Date	6/16/00
Residence: City	BOONB	State	NC	Country	USA	Citizenship	USA
Post Office Address 219 EASTRIDGE DR.							
Post Office Address							
City	BOONB	State	NC	ZIP	28607	Country	USA
Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
EDWARD				JENKO			
Inventor's Signature	Ed Jenko					Date	JUNE 19/00
Residence: City	Essex Junction	State	VT	Country	USA	Citizenship	Canada
Post Office Address HAROLD DRIVE Lamore Road.							
Post Office Address							
City	Essex Junction	State	VT	ZIP	05452	Country	USA.

Burden Hour Statement: This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.


Please type a plus sign (+) inside this box → ☐

PTO/SB/02A (3-97)
Approved for use through 9/30/98 OMB 0651-0032
Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

+

DECLARATION

ADDITIONAL INVENTOR(S) Supplemental Sheet Page 2 of 2

Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
Jim				Pilavdzic			
Inventor's Signature						Date	6/16/00
Residence: City	MILTON	State	VT	Country	USA	Citizenship	Canada
Post Office Address 11 COUNTRY LANE							
Post Office Address							
City	MILTON	State	VT	ZIP	05401	Country	USA
Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
Inventor's Signature						Date	
Residence: City		State		Country		Citizenship	
Post Office Address							
Post Office Address							
City		State		ZIP		Country	
Name of Additional Joint Inventor, if any:		<input type="checkbox"/> A petition has been filed for this unsigned inventor					
Given Name (first and middle [if any])				Family Name or Surname			
Inventor's Signature						Date	
Residence: City		State		Country		Citizenship	
Post Office Address							
Post Office Address							
City		State		ZIP		Country	

Burden Hour Statement This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO Assistant Commissioner for Patents, Washington, DC 20231

+